

A

B

C

SY99 OVERALL CIRCUIT DIAGRAM 3/3 (DM2 2/2, PNAB, PNC

1

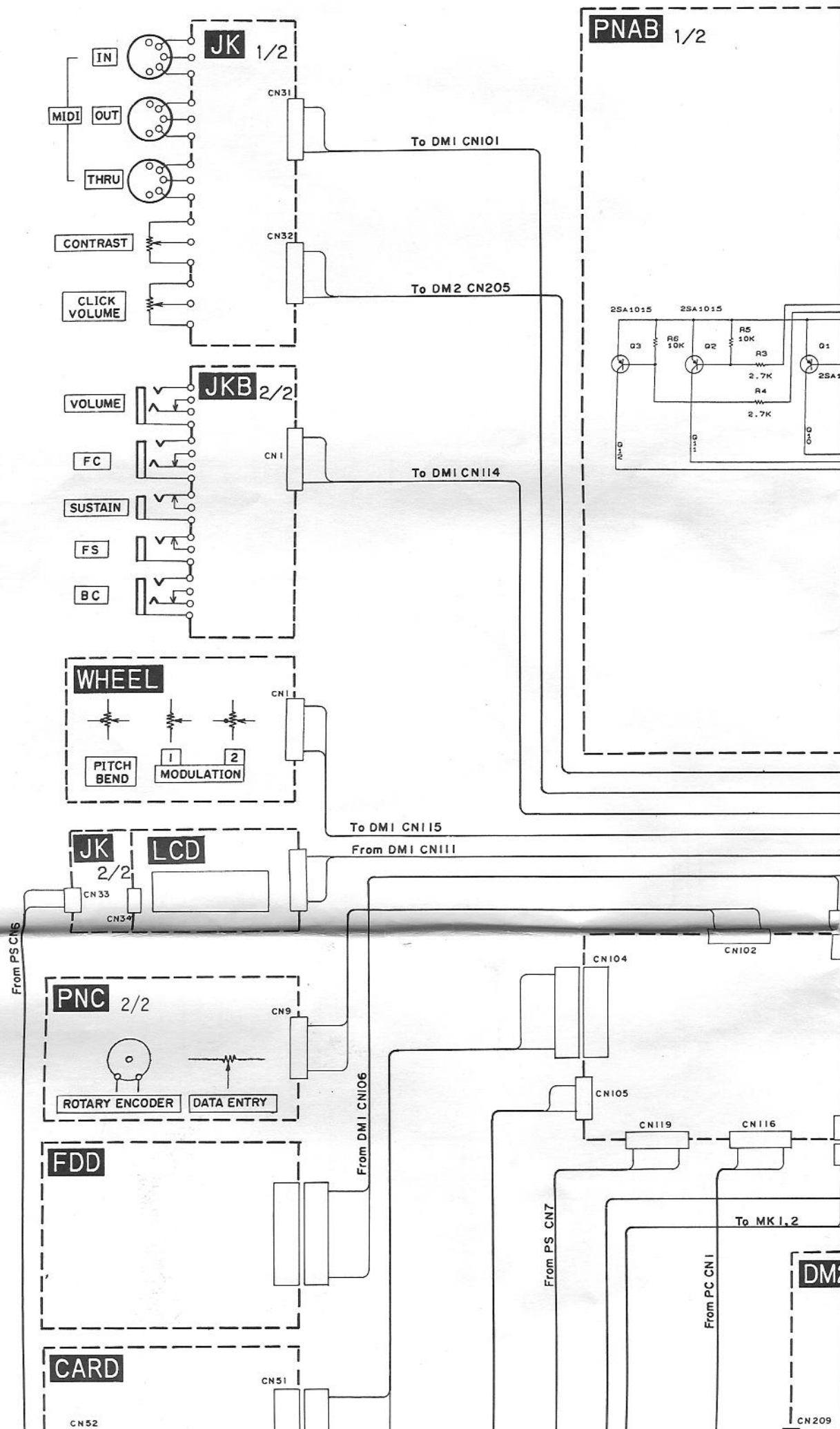
2

3

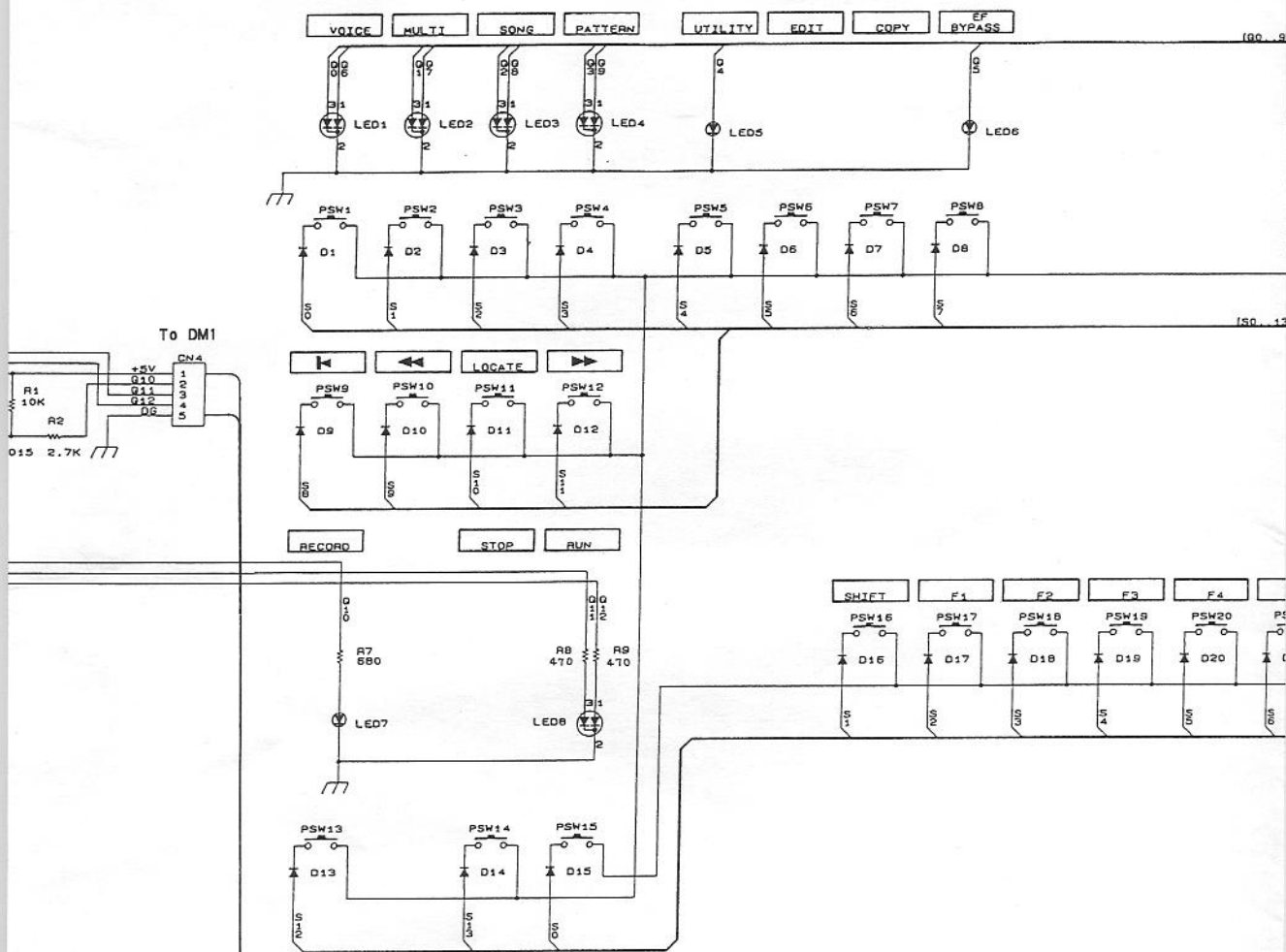
4

5

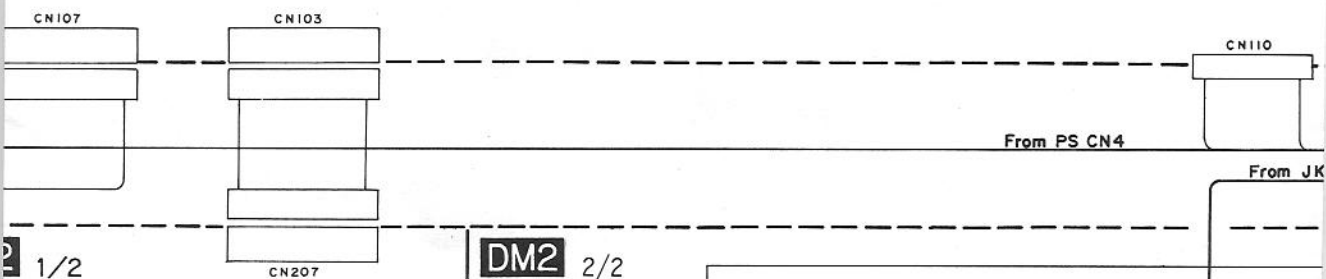
6



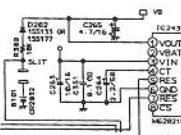
1/2, PC, JKB 1/2, MK1, MK2)



DM1



DM2 2/2



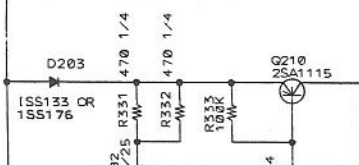
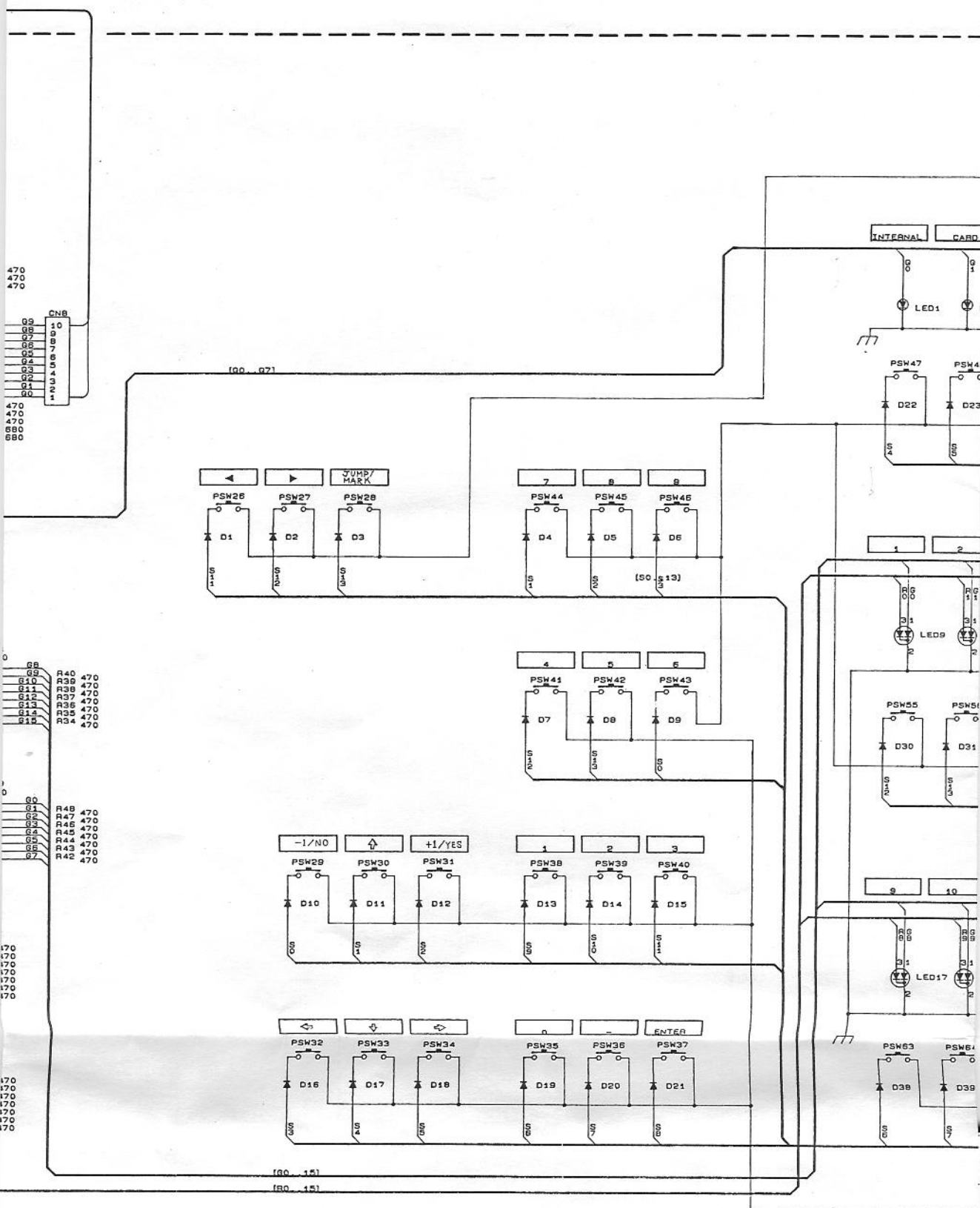


K

L

M

N



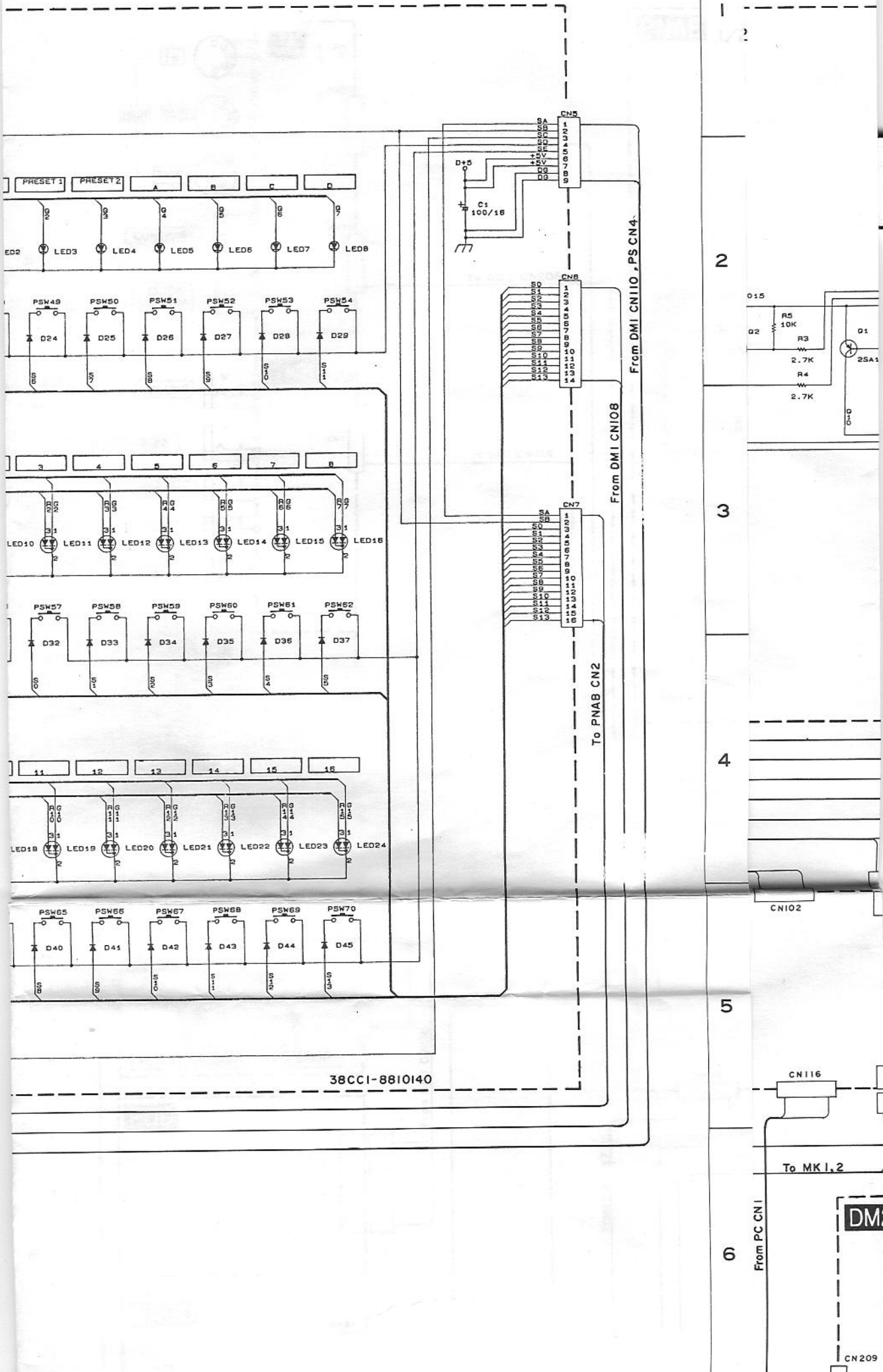
O

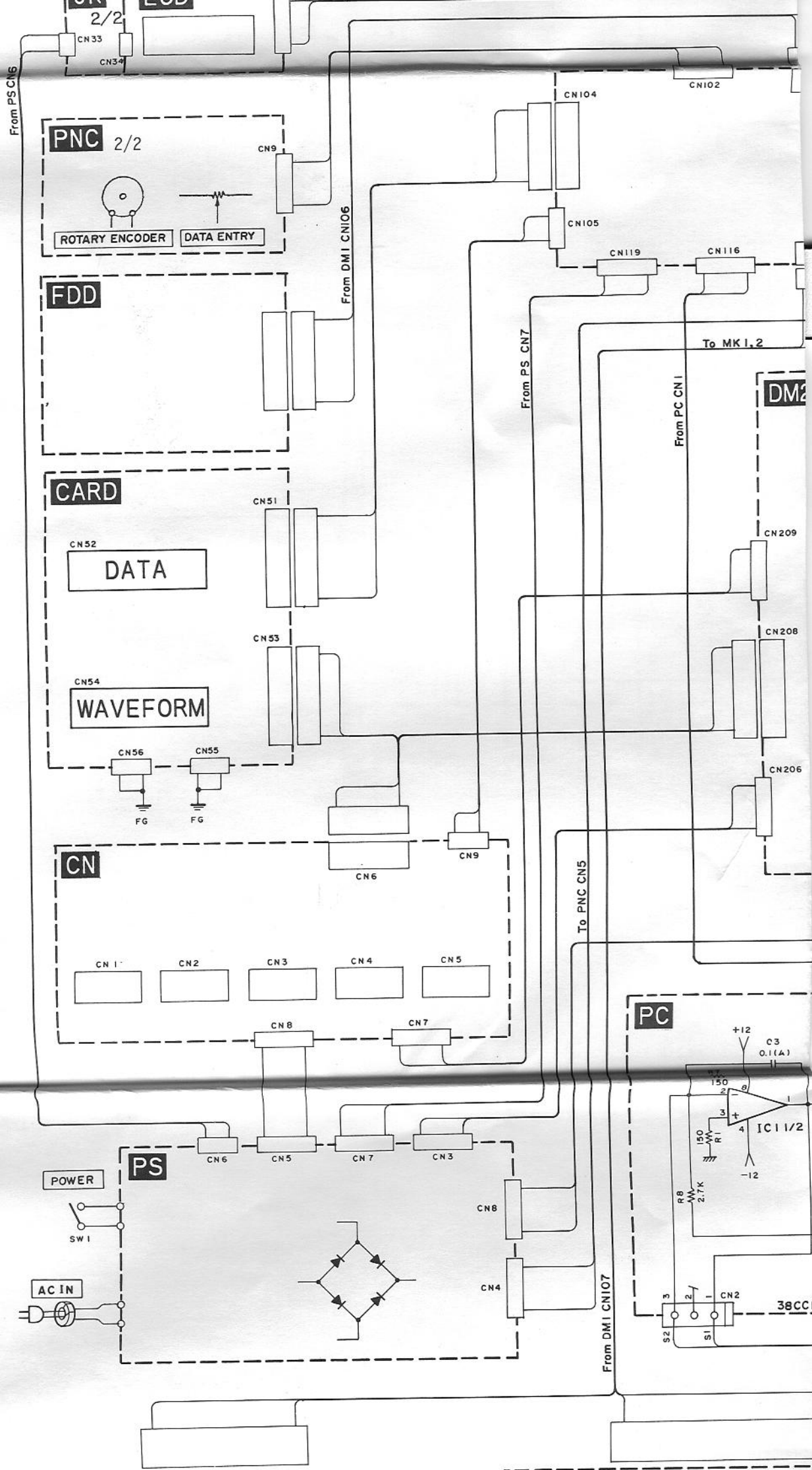
P

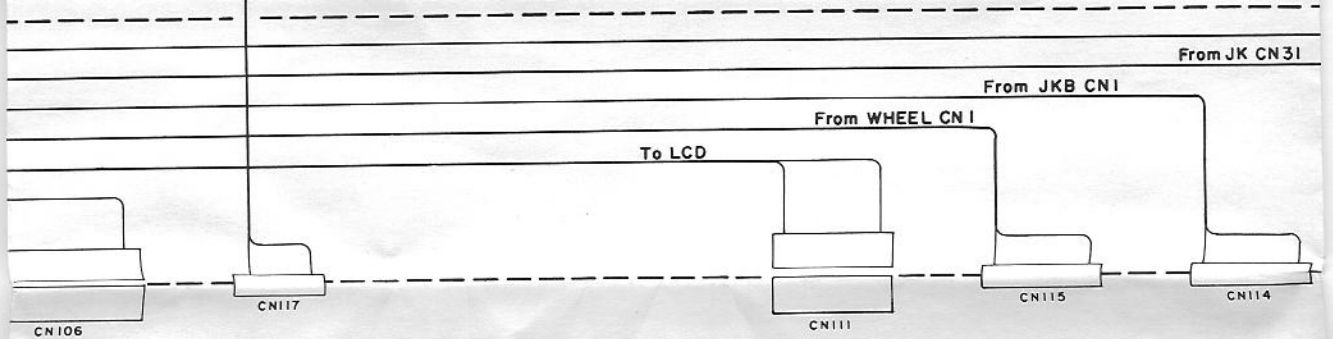
Q

SY99

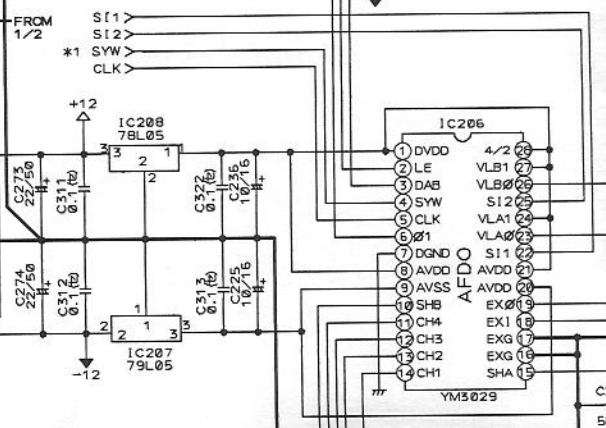
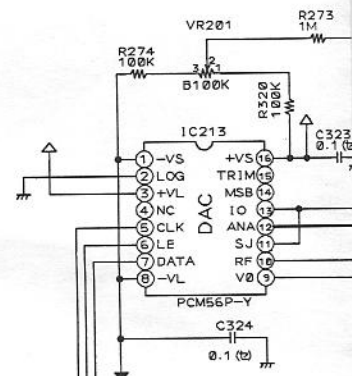
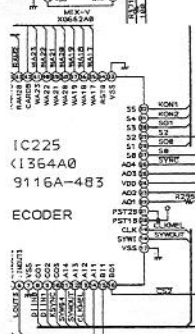
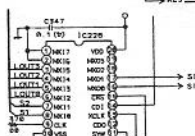
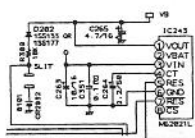
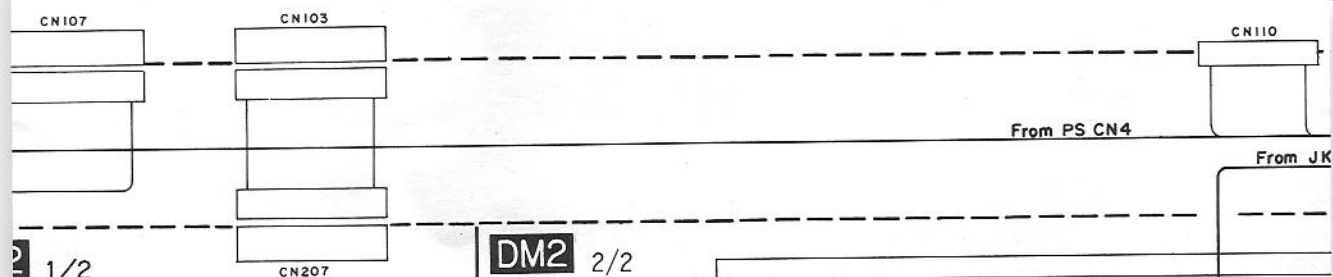
NAB, PNC







DM1



TO PS

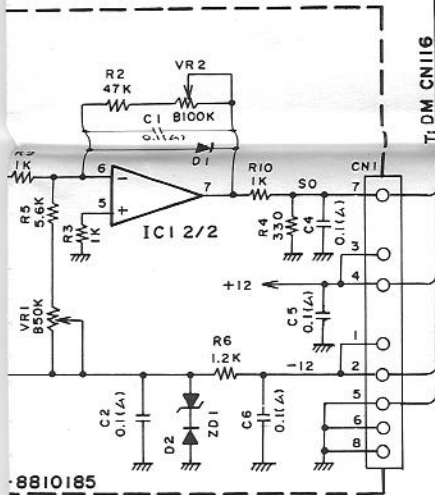
(CN204-1) +12

(CN204-2) AG

(CN204-3) AG

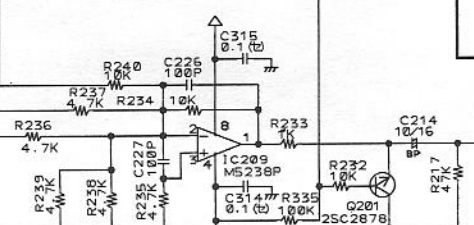
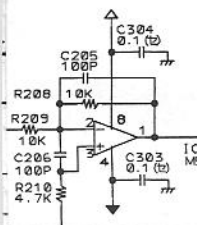
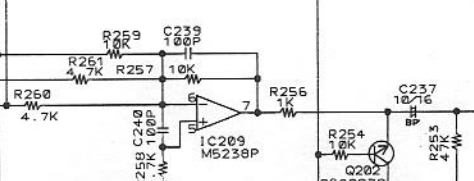
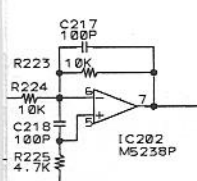
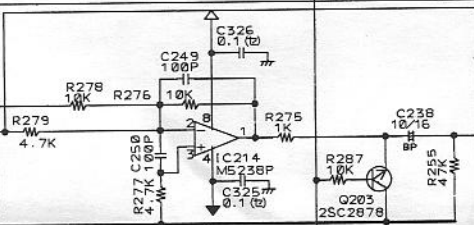
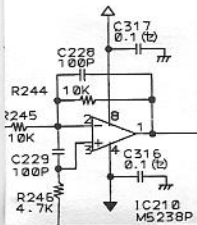
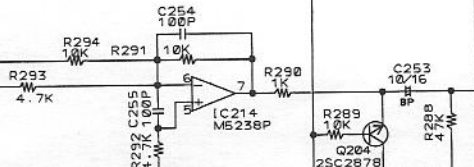
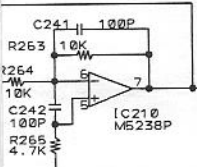
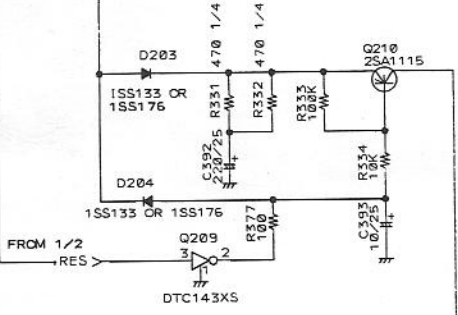
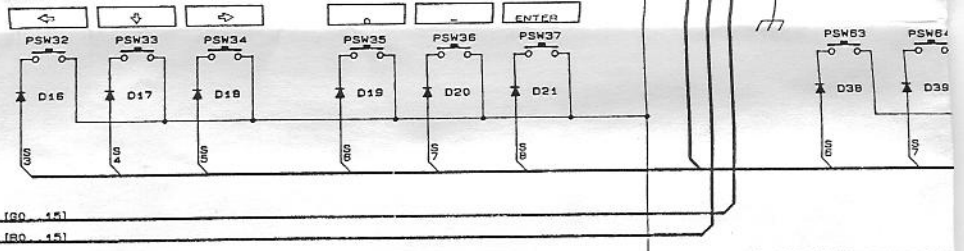
(CN204-4) -12

(CN204-5) MT



PNAB 2/2

170
170
170
170
170
170

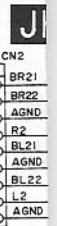


TO JKB

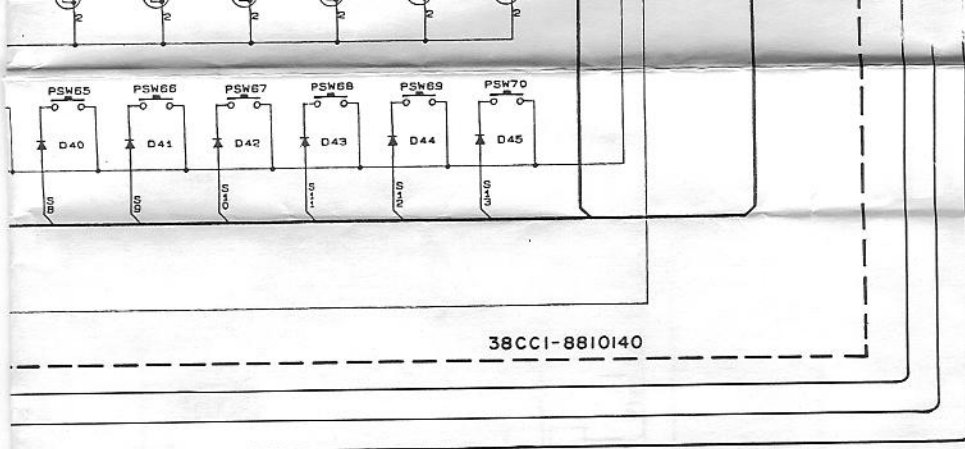
TO JKB

- BR21 (CN201-1)
- BR22 (CN201-2)
- AGND (CN201-3)
- R2 (CN201-4)
- BL21 (CN201-5)
- AGND (CN201-6)
- BL22 (CN201-7)
- L2 (CN201-8)
- AGND (CN201-9)

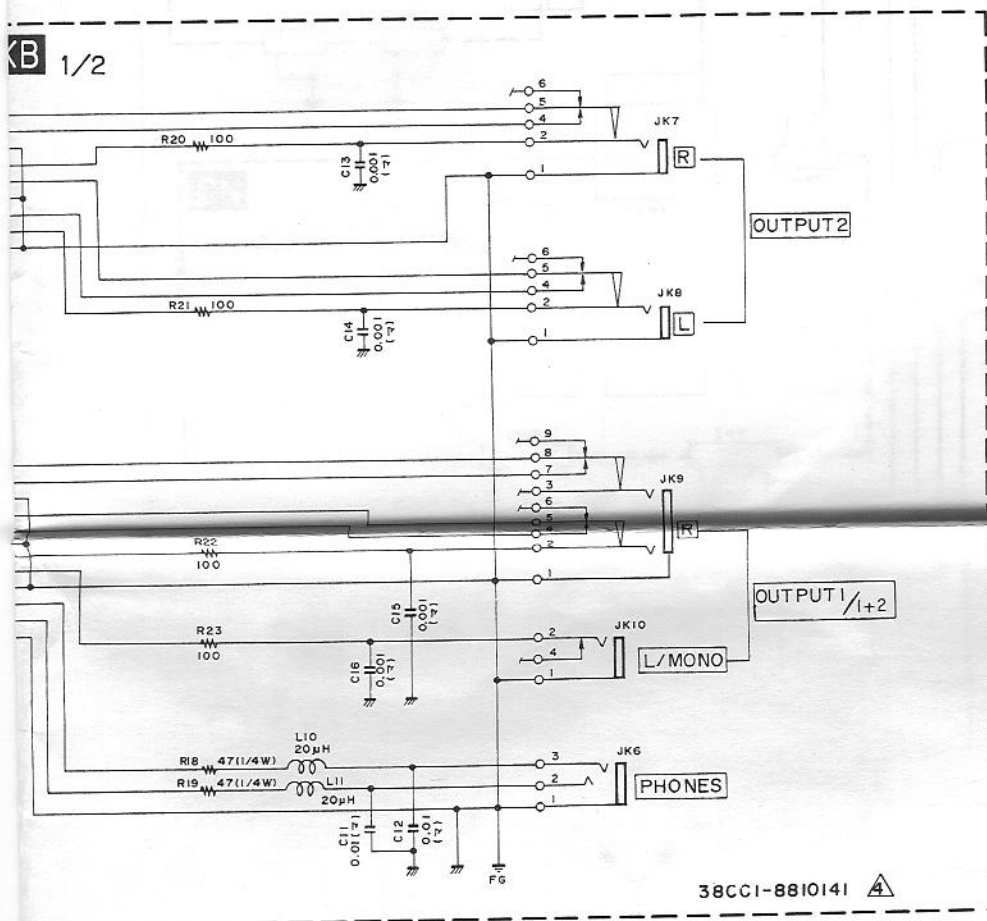
- BR11 (CN202-1)
- BR12 (CN202-2)
- AGND (CN202-3)
- BR13 (CN202-4)
- BR14 (CN202-5)
- AGND (CN202-6)
- R1 (CN202-7)
- L1 (CN202-8)
- AGND (CN202-9)
- HL (CN202-10)
- HR (CN202-11)
- HGND (CN202-12)



IC244 - 247:
IC248:
IC249:
IC250:
IC251:
IC252:
IC253:



38CCI-8810140



38CCI-8810141 A

5

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8

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10

CN102

CN116

To MK I, 2

From PC CN1

DM2

CN209

CN208

CN206

+12
C3
0.1 (A)

IC1 1/2

2.7K

CN2

38CCI-

HM628128LP-10 (X1580A00) SRAM 1M
TC538200P-H100 (X1735B00) ROM 8M
MB838200-20P-G (X1734A00) ROM 8M

8. Semiconductive Cera. Cap.
C399 - 404; 0.1 μ 25V Z (VC694800)
9. Chip Monolithic Cera. Cap.

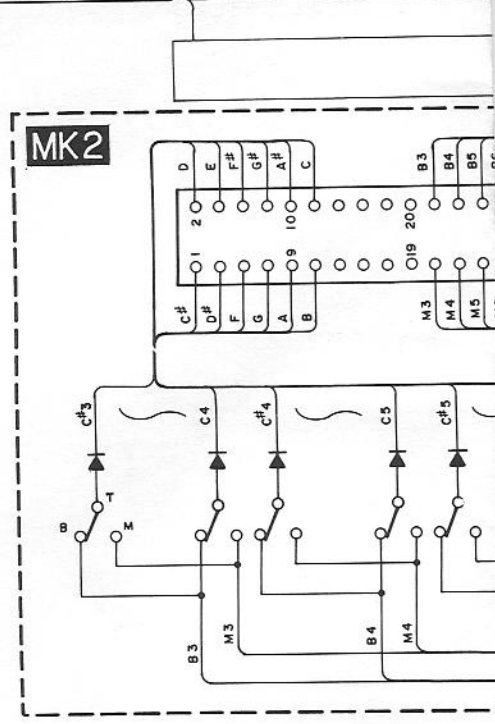
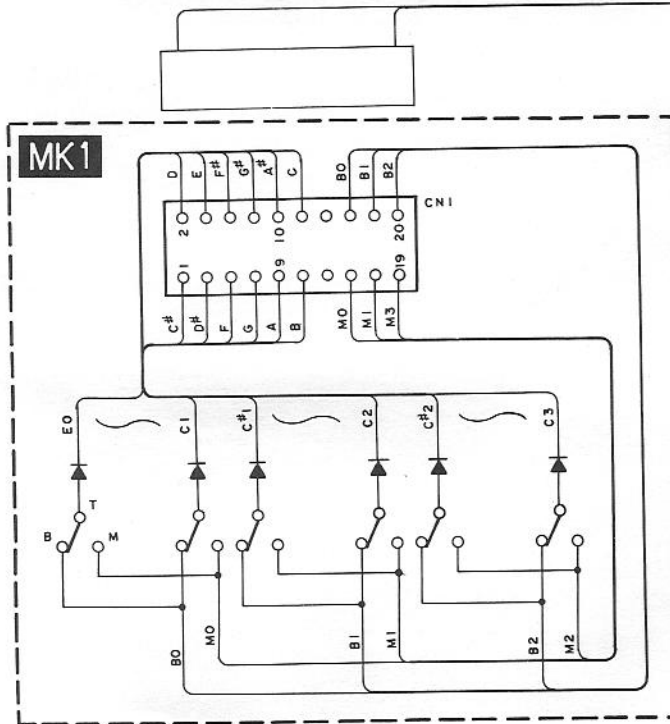
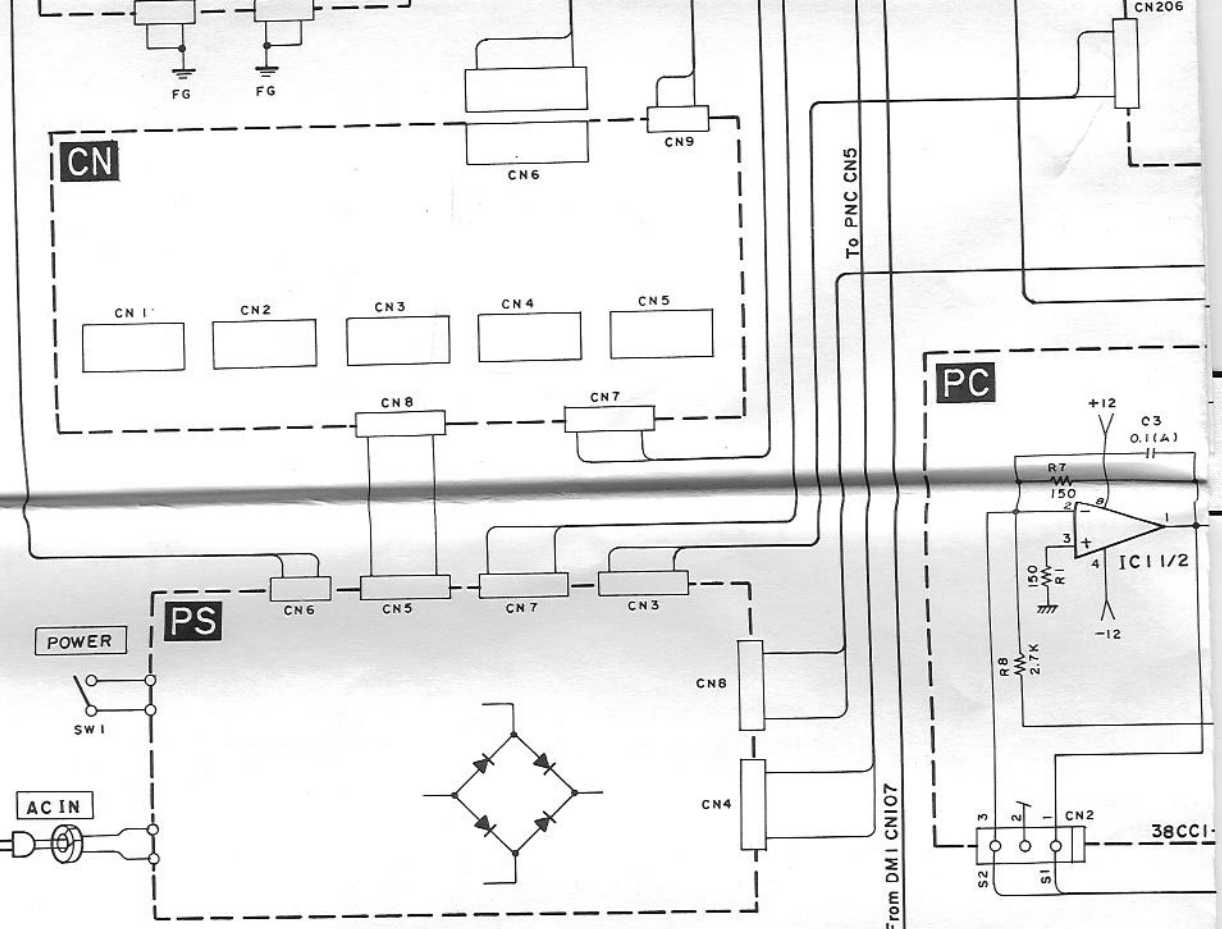
8

9

10

11

12

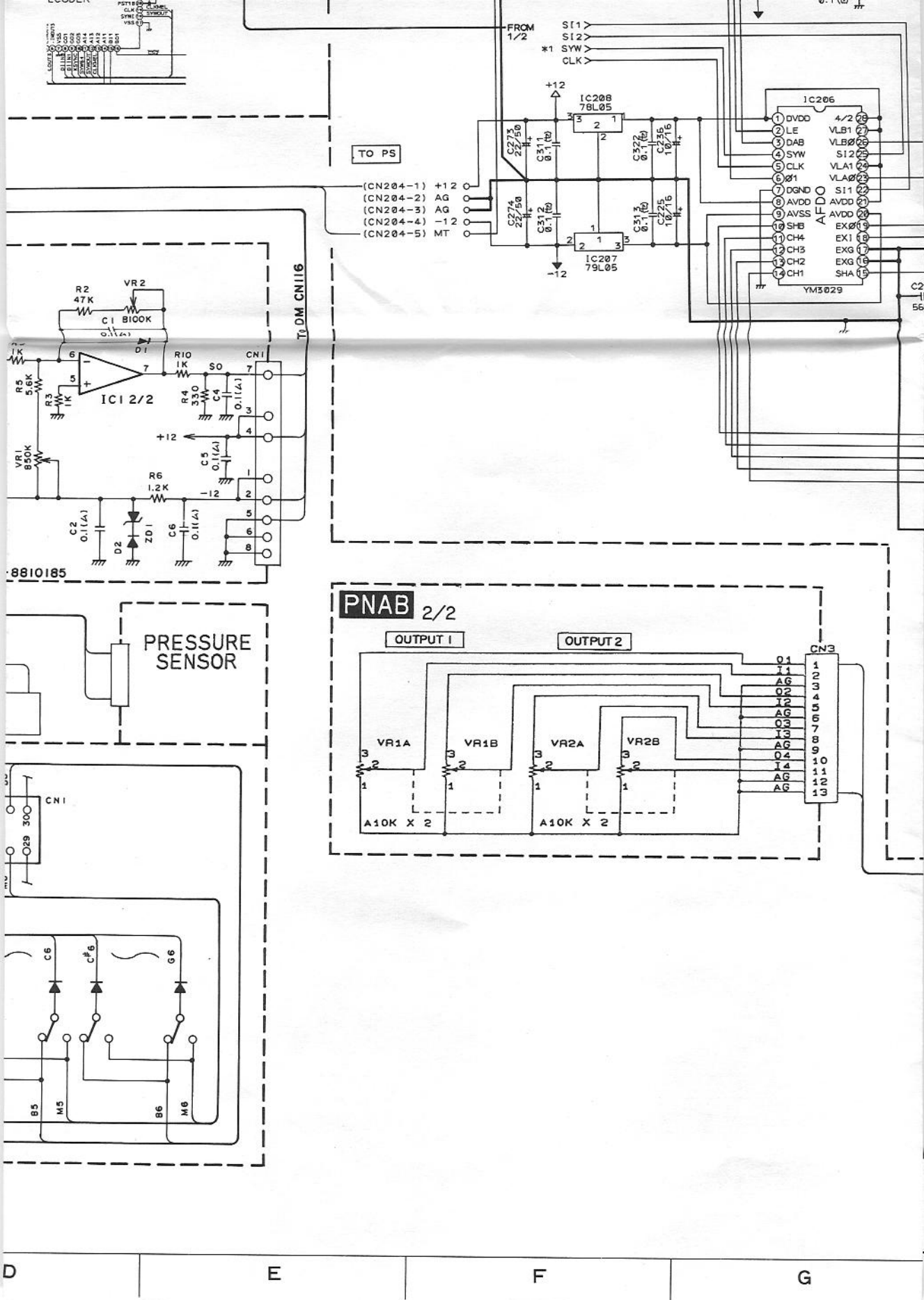


SY99

A

B

C



1



2. Transistor
Q201 ~ 208:
Q210:
3. Digital Transi
Q209:
4. Diode
D202 ~ 204:
5. Resistor Arra
RA201 ~ 203
205 ~ 211
RA204, 212
6. Trimmer Pot
VR201:
7. Chip Resisto
R348 ~ 363:

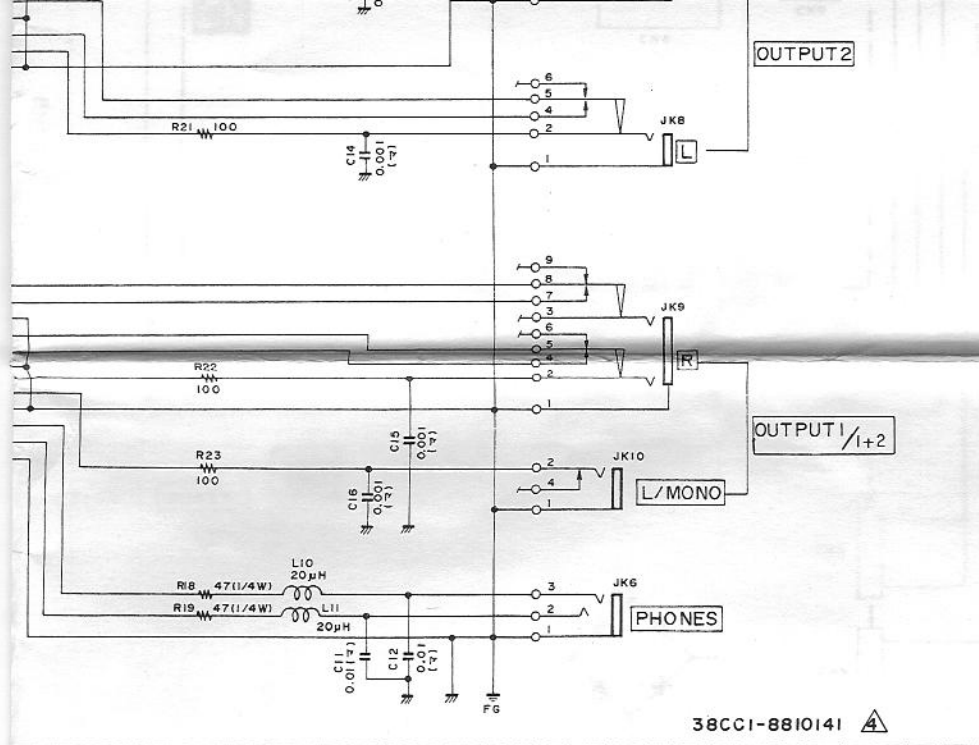
hes

K

L

M

N



HM628128LP-10 (X1580A00) SRAM 1M
 TC538200P-H100 (X1735B00) ROM 8M
 MB8838200-20P-G (X1734A00) ROM 8M
 MB8838200-20P-G (X1733A00) ROM 8M
 MB8838200-20P-G (X1732A00) ROM 8M
 TC538200P-H099 (X1731B00) ROM 8M
 LH538089 (X1730A00) ROM 8M
 LH538088 (X1729A00) ROM 8M
 LH538087 (X1728A00) ROM 8M
 YM7119 (XG995A00) M3
 SN74ALS245ANSR (XE057A00) BUFFER
 SN74LS245ANSR (XH779A00) BUFFER
 TC74HC245F-T1 (XD603A00) TRANSCEIVER
 TC74HC00AF-TP1 (XD655A00) NAND
 SN74HC74NSR (XC726001) DFF
 TC74HC4051AF (XJ623A00) MULTIPLEXER
 SN74HC138NSR (XD835A00) DECODER
 TC74HC21AF (XJ622A00) 2-4 IN AND
 TC74HC175AF-TP1 (XD658A00) DFF

2SC2878 A, B (IC287820)
 2SA1115 E, F (IA111510)
 DTC143XS TP (VD488500)
 1SS133 (IF003450)
 RGLD8X103J (VE445200)
 RGLD4X103J (VE443500)
 B100K EVN (VB593200)
 100Ω 0.1W J (RD255100)

8. Semiconductive Cera. Cap.
 C399 ~ 404: 0.1μ 25V Z (VC694800)
9. Chip Monolithic Cera. Cap.
 C301 ~ 357, 359 ~ 388, 394 ~ 398: F 0.1μ 25V Z (VJ798800)
10. EMI Filter
 EMI 201: LS MT Y223NB (FZ006970)
11. Quartz Crystal Unit
 X201: AF2138CG (VI552000) 12.288MHz
12. Lithium Battery
 B101: SONY/CR2032 (VE338400)

Notes

- Circuit Board: JK (JKB) (NX809700) X1138D0
1. Coil
 L 1 ~ 11: 20μH FL5R200QN (VB835000)
 2. Phone Jack
 JK 1:
 JK 2, 3:
 JK 4, 5, 10:
 JK 6:
 JK 7, 8:
 JK 9:
 ST.MINI HSJ0912 (LB302010) BREATH
 STEREO HLJ4306 (VE742200) F.VOLUME, F.CONT
 MONO HLJ4306 (VE742000) SUS. F.SW, OUTP1 (L)
 STEREO HLJ0521 (LB203090) PHONES
 STEREO HLJ4306 (VI662400) OUTPUT 2 (L, R)
 STEREO HLJ4306 (LB301780) OUTPUT 1/1 + 2 (R)
 3. Ferrite Core
 FR 1: FR25/15/12-1400 (VC362700)

SY99